Workshop III: Deep-dive into Soldering Process and Ideas for Optimization

16.02.21

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SUMMARY

Dr. Majid Mortazavi: "The workshop gave us an unique opportunity to exchange ideas with other experts on the field on the complex topic of Optimization of Solder Printing. We were able to receive interesting insights, based on which we are making some concrete actionable decisions. One that stood on top is conducting a semi-Controlled Experiment particularly focusing on paste (age, type) and stencil condition (old, new), two parameters that are less known in our process, in order to find out their impact on the process. Furthermore, it was suggested that we may look into identifying patterns between similar-looking PCB layouts and distinct solder error types, which may potentially uncover other aspects of the process."

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